<table>
<thead>
<tr>
<th>LAYER NAME</th>
<th>TOP BOARD DESIGN</th>
<th>BOM DN</th>
<th>BOM RND</th>
<th>SHP RND</th>
<th>SHR RND</th>
<th>NOT IN VERSION CONTROL</th>
</tr>
</thead>
<tbody>
<tr>
<td>ALL MASTERS</td>
<td>FROM TOP SIDE</td>
<td>200 &amp; 90200 &amp; 50</td>
<td>RND A</td>
<td>Y/N</td>
<td>Y/N</td>
<td>NOT IN VERSION CONTROL</td>
</tr>
</tbody>
</table>

**Notes:**
- TOP BOARD DESIGN: Y/N
- BOM RND: RND A
- BOM DN: 200 & 90200 & 50
- SHP RND: 50
- SHR RND: RND A
- NOT IN VERSION CONTROL: Y/N

**Generated:** 12-8-2016

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